

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

- 1 7. A method of making a semiconductor device, the method comprising:
2 providing a leadframe comprising:
3 performing a laser cut;
4 testing the semiconductor device; and
5 placing the semiconductor onto tape on a reel.
- 1 8. A method in accordance with claim 7 wherein the testing comprises isolating the
2 gate pad and strip testing prior to performing the laser cut.
- 1 9. A method in accordance with claim 7 further comprising performing an underfill
2 application and a cure after reflowing the solder bumps.
- 1 10. A method in accordance with claim 9 further comprising performing an underfill
2 application and a cure after reflowing the solder bumps.